



Date: 29th Sept, 2014

**Data Sheet Issue: 3** 

## **Thyristor/Diode Modules M## 552**

**Absolute Maximum Ratings** 

Vrrm Vdrm [V]			
	MCC	MCD	MDC
1200	552-12io2	552-12io2	552-12io2
1400	552-14io2	552-14io2	552-14io2
1600	552-16io2	552-16io2	552-16io2

	VOLTAGE RATINGS	MAXIMUM LIMITS	UNITS
V <sub>DRM</sub>	Repetitive peak off-state voltage <sup>1)</sup>	1200-1600	V
Vdsm	Non-repetitive peak off-state voltage 1)	1300-1700	V
V <sub>RRM</sub>	Repetitive peak reverse voltage 1)	1200-1600	V
Vrsm	Non-repetitive peak reverse voltage 1)	1300-1700	V

	OTHER RATINGS	MAXIMUM LIMITS	UNITS
Ιτ(αν)Μ	Maximum average on-state current, $T_C = 85^{\circ}C^{2}$	550	А
Ιτ(αν)Μ	Maximum average on-state current. $T_C = 100^{\circ}C^{2}$	380	А
IT(RMS)M	Nominal RMS on-state current, $T_c = 55^{\circ}C^{2}$	1300	А
I <sub>T(d.c.)</sub>	D.C. on-state current, $T_C = 55^{\circ}C$	1035	А
Ітѕм	Peak non-repetitive surge $t_p = 10 \text{ ms}$ , $V_{RM} = 60\% V_{RRM}$ <sup>3)</sup>	15.8	kA
Ітѕм2	Peak non-repetitive surge $t_p = 10$ ms, $V_{RM} \le 10V^{3}$	17.5	kA
l²t	$I^{2}t$ capacity for fusing $t_{p} = 10$ ms, $V_{RM} = 60\% V_{RRM}$ <sup>3)</sup>	1.25×10 <sup>6</sup>	A <sup>2</sup> s
l²t	$I^{2}t$ capacity for fusing $t_{p}$ = 10 ms, $V_{RM} \leq$ 10 V $^{3)}$	1.53×10 <sup>6</sup>	A <sup>2</sup> s
(d;/dt)	Critical rate of rise of on-state current (repetitive) <sup>4)</sup>	200	A/µs
(di/dt) <sub>cr</sub>	Critical rate of rise of on-state current (non-repetitive) 4)	400	A/µs
V <sub>RGM</sub>	Peak reverse gate voltage	5	V
P <sub>G(AV)</sub>	Mean forward gate power	4	W
Рсм	Peak forward gate power	30	W
VISOL	Isolation Voltage <sup>5)</sup>	3000	V
Тиј ор	Operating temperature range	-40 to +125	°C
T <sub>stg</sub>	Storage temperature range	-40 to +125	°C

#### Notes:

1) De-rating factor of 0.13% per °C is applicable for  $T_{vj}$  below 25°C.

2) Single phase; 50 Hz, 180° half-sinewave.

3) Half-sinewave, 125°C T<sub>vj</sub> initial.

4)  $V_D = 67\% V_{DRM}$ ,  $I_{FG} = 2 \text{ A}$ ,  $t_r \le 0.5 \mu s$ ,  $T_C = 125^{\circ}C$ .

5) AC RMS voltage, 50 Hz, 1min test

## **Characteristics**

	PARAMETER	MIN.	TYP.	MAX.	TEST CONDITIONS <sup>1)</sup>	UNITS	
Vтм	Maximum peak on-state voltage	-	-	1.40	I <sub>TM</sub> = 1700 A	V	
V <sub>TM</sub>	Maximum peak on-state voltage	-	-	1.33	I <sub>TM</sub> = 1500 A	V	
V <sub>T0</sub>	Threshold voltage	-	-	0.770		V	
r⊤	Slope resistance	-	-	0.259		mΩ	
(dv/dt) <sub>cr</sub>	Critical rate of rise of off-state voltage	1000	-	-	V <sub>D</sub> = 80% V <sub>DRM</sub> , linear ramp, Gate o/c	V/µs	
Idrm	Peak off-state current	-	-	100	Rated V <sub>DRM</sub>	mA	
I <sub>RRM</sub>	Peak reverse current	-	-	100	Rated V <sub>RRM</sub>	mA	
Vgt	Gate trigger voltage	-	-	2.50		V	
I <sub>GT</sub>	Gate trigger current	-	-	250	$T_{vj} = 25^{\circ}C, V_{D} = 12 V, I_{T} = 3 A$	mA	
V <sub>GD</sub>	Gate non-trigger voltage	0.25	-	-	67% V <sub>DRM</sub>	V	
Ін	Holding current	-	-	300	$V_D = 12 V, T_{vj} = 25^{\circ}C$	mA	
t <sub>gd</sub>	Gate controlled turn-on delay time	-	0.5	1.0	I <sub>FG</sub> = 2 A, t <sub>r</sub> = 0.5 μs, V <sub>D</sub> = 67%V <sub>DRM</sub> ,		
t <sub>gt</sub>	Turn-on time	-	1.0	2.0	I <sub>TM</sub> = 2000 A, di/dt = 10 A/μs, T <sub>vj</sub> = 25°C	μs	
Qrr	Recovered Charge	-	2000	2250		μC	
Q <sub>ra</sub>	Recovered Charge, 50% chord	-	1600	-	I <sub>TM</sub> = 550 A, di/dt = 10A/µs,	μC	
Irm	Reverse recovery current	-	140	-	$V_{\rm R} = 100 \text{ V}$		
trr	Reverse recovery time, 50% chord	-	23	-		μs	
	Turn off time	-	180	-	I <sub>TM</sub> = 550 A, di/dt = 10 A/µs, V <sub>R</sub> = 100 V, V <sub>DR</sub> = 67%V <sub>DRM</sub> , dv <sub>DR</sub> /dt = 20 V/µs		
tq	Turn-off time	-	240	-	I <sub>TM</sub> = 550 A, di/dt = 10 A/µs, V <sub>R</sub> = 100 V, V <sub>DR</sub> = 67%V <sub>DRM</sub> , dv <sub>DR</sub> /dt = 200 V/µs	μs	
<b>D</b>		-	-	0.062	Single Thyristor	K/W	
R <sub>thJC</sub>	Thermal resistance, junction to case	-	-	0.031	Whole Module	K/W	
<b>D</b>	The second se	-	-	0.02	Single Thyristor	K/W	
R <sub>thCH</sub>	Thermal resistance, case to heatsink	-	-	0.01	Whole Module	K/W	
F <sub>1</sub>	Mounting force (to heatsink)	4.25	-	5.75		Nm	
F2	Mounting force (to terminals)	10.2	-	13.8	2)	Nm	
Wt	Weight	-	1.5	-		kg	

Notes:

1) Unless otherwise indicated  $T_{vj}$ =125°C. 2) Screws must be lubricated.

#### **Notes on Ratings and Characteristics**

#### 1.0 Voltage Grade Table

Voltage Grade	V <sub>drm</sub> V <sub>rrm</sub> V	V <sub>DSM</sub> V <sub>RSM</sub> V	V <sub>D</sub> V <sub>R</sub> DC V
12	1200	1300	900
14	1400	1500	1050
16	1600	1700	1200

#### 2.0 Extension of Voltage Grades

This report is applicable to other voltage grades when supply has been agreed by Sales/Production.

#### 3.0 De-rating Factor

A blocking voltage de-rating factor of 0.13%/°C is applicable to this device for T<sub>vj</sub> below 25°C.

#### 4.0 Repetitive dv/dt

Standard dv/dt is 1000V/µs.

#### 5.0 Snubber Components

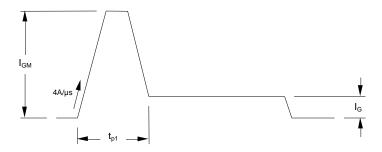
When selecting snubber components, care must be taken not to use excessively large values of snubber capacitor or excessively small values of snubber resistor. Such excessive component values may lead to device damage due to the large resultant values of snubber discharge current. If required, please consult the factory for assistance.

#### 6.0 Rate of rise of on-state current

The maximum un-primed rate of rise of on-state current must not exceed 400A/µs at any time during turnon on a non-repetitive basis. For repetitive performance, the on-state rate of rise of current must not exceed 200A/µs at any time during turn-on. Note that these values of rate of rise of current apply to the total device current including that from any local snubber network.

#### 7.0 Gate Drive

The nominal requirement for a typical gate drive is illustrated below. An open circuit voltage of at least 30V is assumed. This gate drive must be applied when using the full di/dt capability of the device.



The magnitude of  $I_{GM}$  should be between five and ten times  $I_{GT}$ , which is shown on page 2. Its duration  $(t_{p1})$  should be 20µs or sufficient to allow the anode current to reach ten times  $I_L$ , whichever is greater. Otherwise, an increase in pulse current could be needed to supply the necessary charge to trigger. The 'back-porch' current  $I_G$  should remain flowing for the same duration as the anode current and have a magnitude in the order of 1.5 times  $I_{GT}$ .

 $W_{AV} = \frac{\Delta T}{R_{th}}$  $\Delta T = T_{j \max} - T_{K}$ 

## 8.0 Computer Modelling Parameters

## 8.1 Thyristor Dissipation Calculations

$$I_{AV} = \frac{-V_{T0} + \sqrt{V_{T0}^{2} + 4 \cdot ff^{2} \cdot r_{T} \cdot W_{AV}}}{2 \cdot ff^{2} \cdot r_{T}}$$

Where  $V_{T0} = 0.770 \text{ V}$ ,  $r_T = 0.259 \text{ m}\Omega$ .

 $R_{th}$  = Supplementary thermal impedance, see table below and

ff = Form factor, see table below.

Supplementary Thermal Impedance							
Conduction Angle 30° 60° 90° 120° 180° 270° d.c.						d.c.	
Square wave	0.0702	0.0685	0.0679	0.0668	0.0658	0.0637	0.0620
Sine wave	0.0677	0.0673	0.0664	0.0655	0.0650		

and:

Form Factors							
Conduction Angle	30°	60°	90°	120°	180°	270°	d.c.
Square wave	3.464	2.449	2	1.732	1.414	1.149	1
Sine wave	3.98	2.778	2.22	1.879	1.57		

8.2 Calculating thyristor VT using ABCD Coefficients

The on-state characteristic  $I_T$  vs.  $V_T$ , on page 6 is represented by a set of constants A, B, C, D, forming the coefficients of the representative equation for  $V_T$  in terms of  $I_T$  given below:

$$V_T = A + B \cdot \ln(I_T) + C \cdot I_T + D \cdot \sqrt{I_T}$$

The constants, derived by curve fitting software, are given below for both hot and cold characteristics. The resulting values for  $V_T$  agree with the true device characteristic over a current range, which is limited to that plotted.

	25°C Coefficients	125°C Coefficients		
Α	1.238754	А	0.5570029	
В	-0.1633889	В	-0.03013580	
С	-3.109066×10 <sup>-6</sup>	С	1.144276×10 <sup>-4</sup>	
D	0.03236259	D	0.02116443	

## 8.3 D.C. Thermal Impedance Calculation

$$r_t = \sum_{p=1}^{p=n} r_p \cdot \left(1 - e^{\frac{-t}{\tau_p}}\right)$$

Where p = 1 to *n* and:

n = number of terms in the series

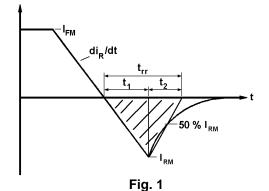
- t = Duration of heating pulse in seconds
- $r_t$  = Thermal resistance at time t
- $r_p$  = Amplitude of  $p_{th}$  term
- $\tau_p$  = Time Constant of r<sub>th</sub> term

The coefficients for this device are shown in the table below:

D.C.								
Term	1	2	3	4	5			
rp	1.37×10 <sup>-3</sup>	4.86×10⁻³	0.0114	0.0223	0.0221			
τρ	7.6×10 <sup>-4</sup>	8.6×10 <sup>-3</sup>	0.101	0.56	3.12			

#### 9.0 Reverse recovery ratings

(i)  $Q_{ra}$  is based on 50%  $I_{RM}$  chord as shown in Fig. 1



(ii)  $Q_{rr}$  is based on a 150 µs integration time i.e.

$$Q_{rr} = \int_{0}^{150\mu s} i_{rr}.dt$$

(iii)

$$K Factor = \frac{t_1}{t_2}$$

## <u>Curves</u>

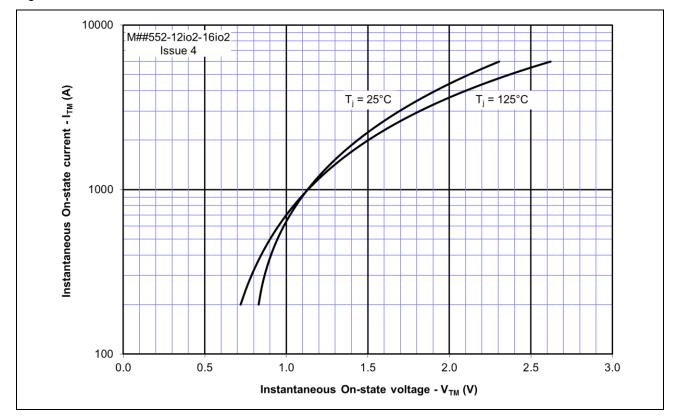
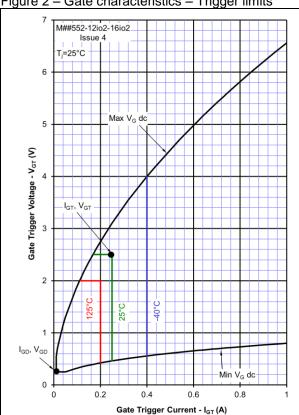


Figure 1 – On-state characteristics of Limit device



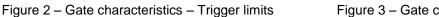
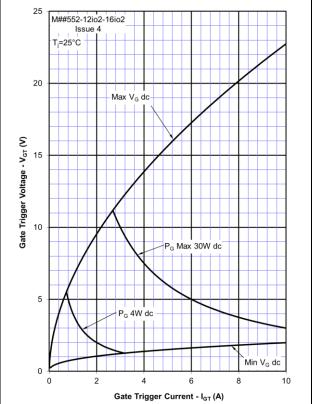
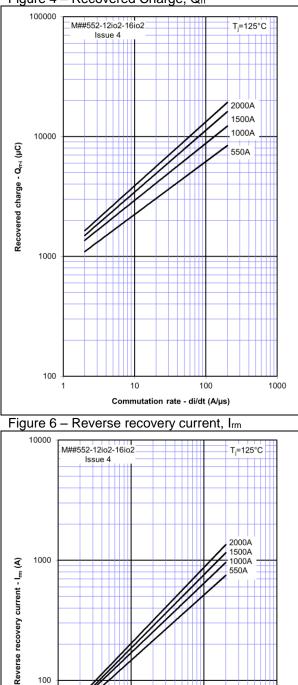
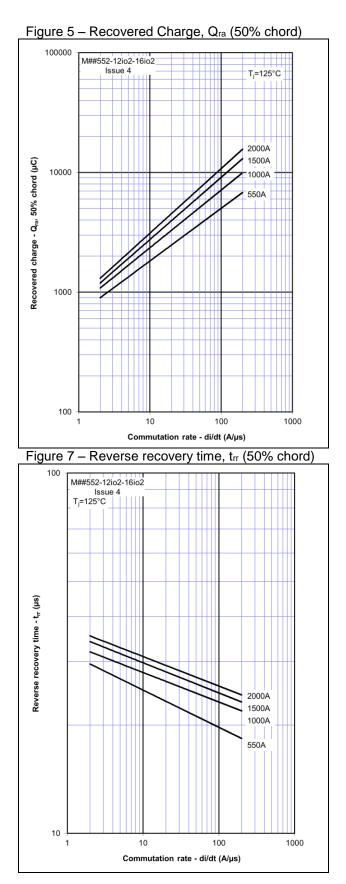


Figure 3 – Gate characteristics – Power curves





## Figure 4 – Recovered Charge, Qrr



10

100

Commutation rate - di/dt (A/µs)

100

10

1

1000

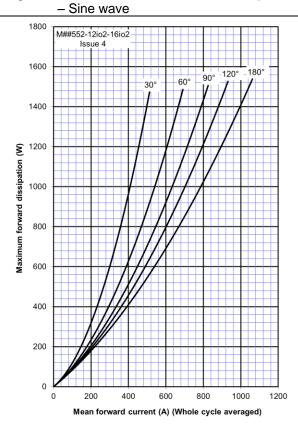


Figure 10 – On-state current vs. Power dissipation

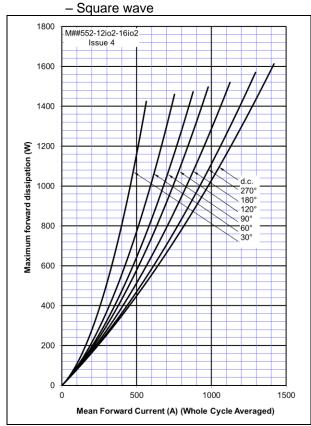


Figure 9 – On-state current vs. case temperature – Sine wave

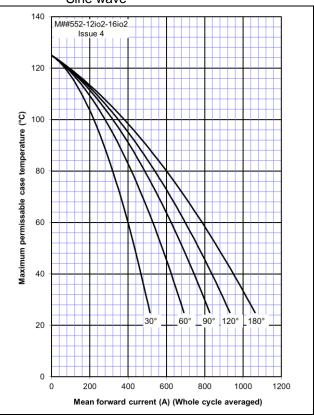
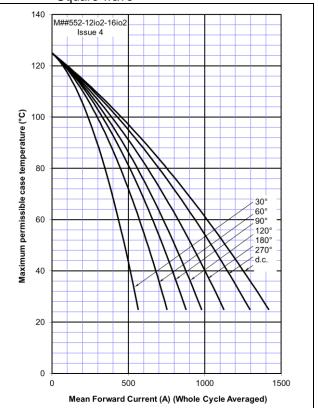
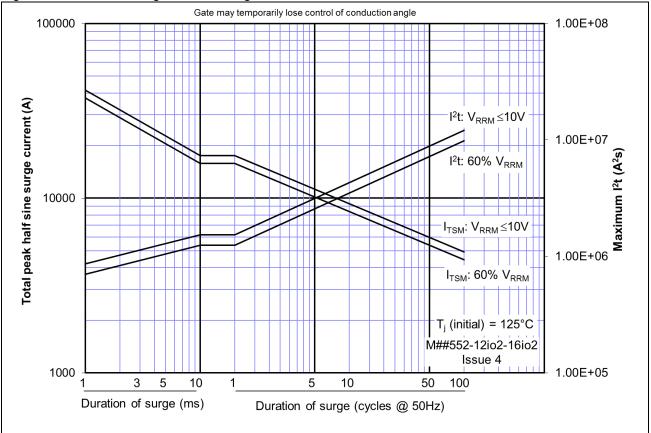


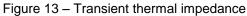
Figure 11 – On-state current vs. case temperature – Square wave

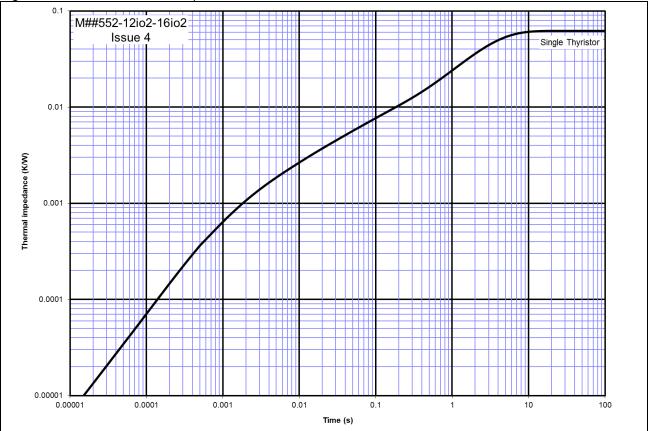


# Figure 8 – On-state current vs. Power dissipation



#### Figure 12 – Maximum surge and I<sup>2</sup>t Ratings





#### **Outline Drawing & Ordering Information**

